

Chemicals contained in products

Package-type

Epson Package name; **QFP5-100PIN-S2/ Halogen free**

JEITA Package name; **P-QFP100-1420-0.65**

Terminal plating; **Lead(Pb) Free**

Weight; **1.76 [g]*Note1**

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	16.1	Silicon	7440-21-3	16.1	999894	Base material
			Boron	7440-42-8	0.000032	2	Dopant
			Phosphorus	7723-14-0	0.000081	5	Dopant
			Aluminum	7429-90-5	0.00032	20	Metalization
			Arsenic *Note3	7440-38-2	0.000081	5	Dopant
			Fluorine *Note3	7782-41-4	0.000032	2	Dopant
			Titanium *Note3	7440-32-6	0.00032	20	Metalization
			Molybdenum *Note3	7439-98-7	0.00032	20	Metalization
			Tungsten *Note3	7440-33-7	0.00048	30	Metalization
			Cobalt *Note3	7440-48-4	0.000032	2	Metalization
	Stress buffer coat	0.3	Polyimide	-	0.3	1000000	Stress buffer coat *Note4
Package	Die Bonding material	2.5	Silver	7440-22-4	1.6	640000	Base material
			Epoxy resin	-	0.51	205000	Adhesive
			Phenol resin	-	0.20	80000	Adhesive
			Inorganic powder	-	0.12	48000	Additive
			Bismuth compound	-	0.068	27000	Ion trap
	Lead Frame Plating	30.3	Tin	7440-31-5	30.3	1000000	Solder
	Lead Frame	366.7	Copper	7440-50-8	346.5	945000	Conductor
			Silver	7440-22-4	1.8	5000	Inner lead plating
			Others *Note5	-	18.3	50000	Additive
	Bonding Wire	2.3	Gold	7440-57-5	2.3	1000000	Conductor
	Mold resin	1341.7	Epoxy resin	-	67.1	50000	Base material
			Silica	60676-86-0/-	1214.2	905000	Filler
			Carbon black	1333-86-4	6.7	5000	Coloring agent
Hardening chemical(ex:Phenol resin)			-	53.7	40000	Base material	

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.

*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included for the Cu type. And the carbon, silicon, and manganese are included for 42alloy type.